



Thermal Silicone Pad



特色 Characteristic

具導熱性 Thermal conductive
高柔軟性及高壓縮性 High soft and compressible
自黏性佳 Excellent natural tack
高耐電壓值 Good insulator
可當緩衝材使用 Shock & vibration absorber
多種厚度可選擇 Available in varies thickness

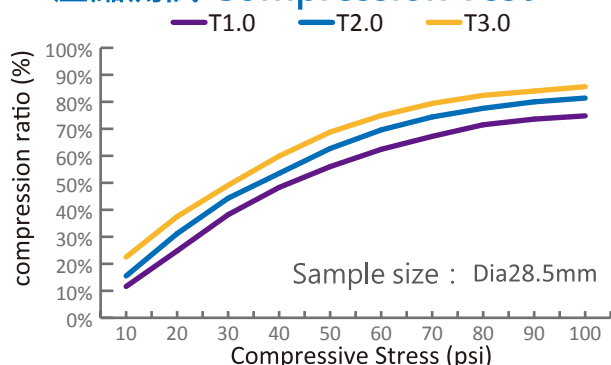
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-17	MP-17D	MP-17FB	Unit	Test Method
顏色 Color	Purple	Gray	Purple+Yellow	---	Visual
厚度 Thickness	0.25~25	0.5~25	0.5~25	mm	ASTM D374
導熱係數 Thermal conductivity	1.7	1.9	1.7	W/mk	ASTM D5470
比重 Specific Gravity	1.8±0.2	1.8±0.2	2.0±0.2	g/cm ³	ASTM D792
延展率 Elongation	75±10	75±10	<1	%	ASTM D412
抗拉強度 Tensile Strength	7±3	7±3	70±5	Kgf/cm ²	ASTM D412
硬度 Hardness	15±5	15±5	15±5	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹³	>10 ¹³	>10 ¹⁴	ohm • cm	ASTM D257
耐電壓 Insulation Strength	>6.0	>6.0	>10	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-45~200	-45~200	°C	---
耐燃等級 Flame Rating	V-0	-	-	---	UL94

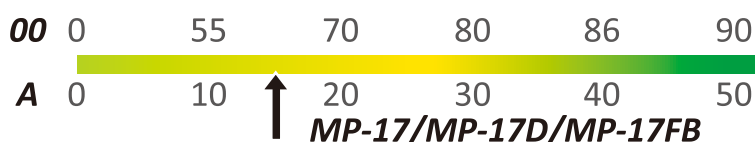
* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

壓縮測試 Compression Test

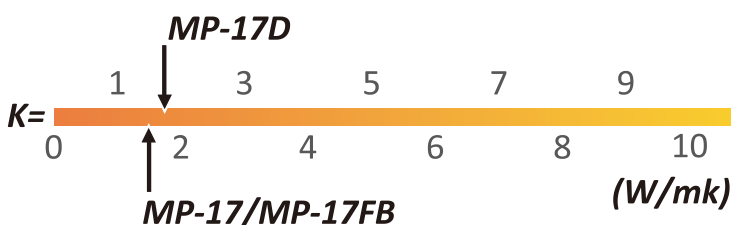


The compression ratio of MP-17 T2.0 at 50 psi is about 62.7%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



備註 Remark

- *MP-17、MP-17FB 可添加玻璃纖維增強機械性 (P/N: MP-17FG、MP-17FGFB)
Can add with fiberglass reinforced.
- *MP-17D 可外加玻璃纖維布增強機械性 (P/N: MP-17DFB)
Can add with fiberglass reinforced.
- *MP-17、MP-17D、MP-17FB 雙面皆可背膠 (A1 / A2)
Can add with adhesive on one or two sides.



Thermal Silicone Pad



特色 Characteristic

- 具導熱性 Thermal conductive
- 高柔軟性及高壓縮性高 High soft and compressible
- 自黏性佳 **Excellent natural tack**
- 高耐電壓值 Good insulator
- 可當緩衝材使用 Shock & vibration absorber
- 多種厚度可選擇 Available in varies thickness

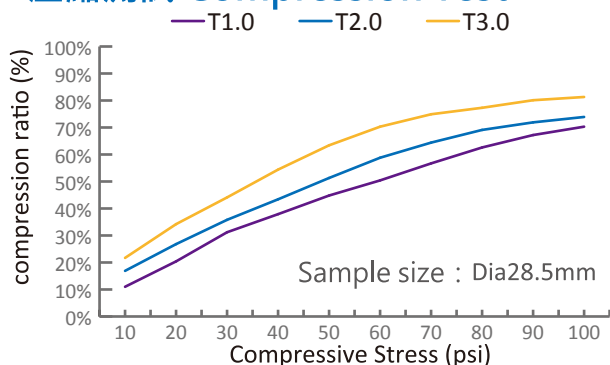
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-19	MP-19Y	MP-19YFB	Unit	Test Method
顏色 Color	Grey	Yellow	Yellow+Yellow	---	Visual
厚度 Thickness	0.25~25	0.25~25	0.5~25	mm	ASTM D374
導熱係數 Thermal conductivity	1.9	1.6	1.6	W/mk	ASTM D5470
比重 Specific Gravity	1.7±0.2	1.7±0.2	2.0±0.2	g/cm ³	ASTM D792
延展率 Elongation	<250±10	<250±10	<1	%	ASTM D412
抗拉強度 Tensile Strength	10±3	3±3	70±5	Kgf/cm ²	ASTM D412
硬度 Hardness	15±3	4±3	4±3	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹³	>10 ¹³	>10 ¹⁴	ohm•cm	ASTM D257
耐電壓 Insulation Strength	>5.0	>5.0	>10	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-45~200	-45~200	°C	---

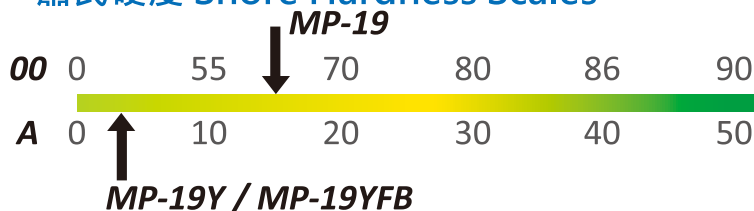
* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

壓縮測試 Compression Test

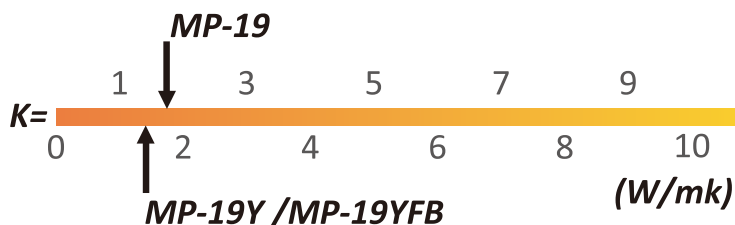


The compression ratio of MP-19 T2.0 at 50 psi is about 51.3%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



備註 Remark

- *可添加玻璃纖維增強機械性
(P/N: MP-19FG、MP-19YFG、MP-19YFGFB)
Can add with fiberglass reinforced.
- *可外加玻璃纖維布增強機械性
(P/N: MP-19FB、MP-19YFB)
Can add with fiberglass reinforced.
- *雙面皆可背膠 (A1 / A2)
Can add with adhesive on one or two sides.





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特色 Characteristic

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高耐電壓值 Good insulator
可當緩衝材使用 Shock & vibration absorber
多種厚度可選擇 Available in varies thickness

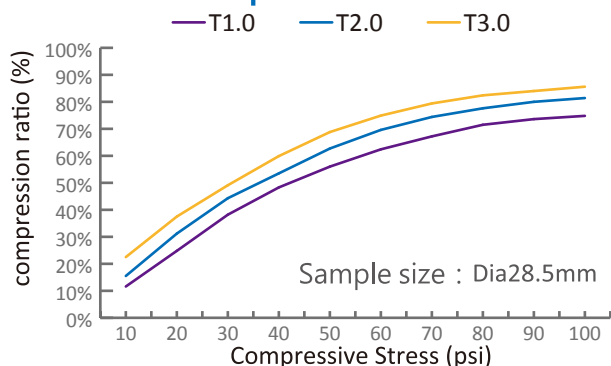
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-25	MP-25Y	MP-25FB	Unit	Test Method
顏色 Color	Green	Green	Green+Yellow	---	Visual
厚度 Thickness	0.25~25	0.25~5.0	0.5~25	mm	ASTM D374
導熱係數 Thermal conductivity	2.2	2.0	2.2	W/mk	ASTM D5470
比重 Specific Gravity	2.1±0.2	2.1±0.2	2.3±0.2	g/cm ³	ASTM D792
延展率 Elongation	<150±10	<250±10	<1	%	ASTM D412
抗拉強度 Tensile Strength	13±3	3±3	70±5	Kgf/cm ²	ASTM D412
硬度 Hardness	18±3	5±3	18±3	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹³	>10 ¹⁵	>10 ¹⁴	ohm•cm	ASTM D257
耐電壓 Insulation Strength	>5.0	>10.0	>10.0	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-45~160	-45~200	°C	---

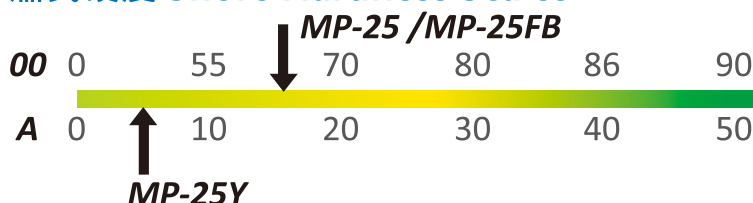
* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

壓縮測試 Compression Test

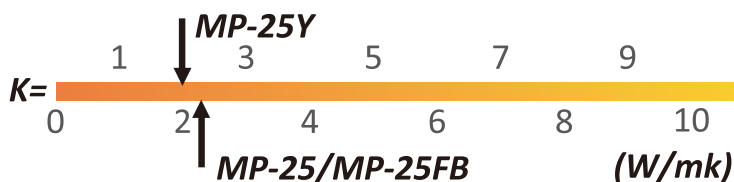


The compression ratio of MP-25 T2.0 at 50 psi is about 62.7%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



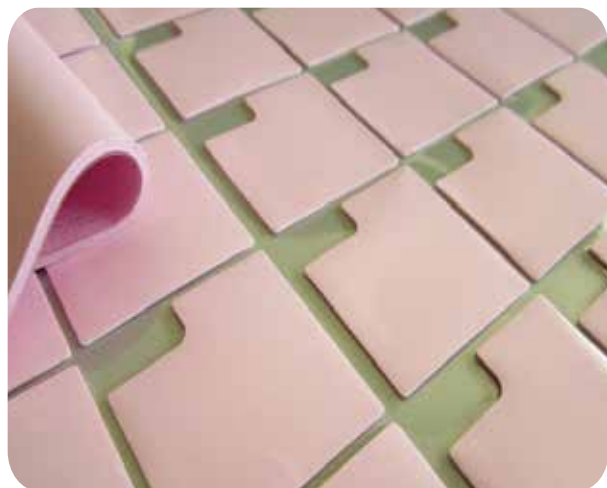
備註 Remark

- *可添加玻璃纖維增強機械性
(P/N: MP-25FG、MP-25YFG、MP-25FGFB)
Can add with fiberglass reinforced.
- *可外加玻璃纖維布增強機械性
(P/N: MP-25FB、MP-25YFB)
Can add with fiberglass reinforced.
- *雙面皆可背膠 (A1 / A2)
Can add with adhesive on one or two sides.





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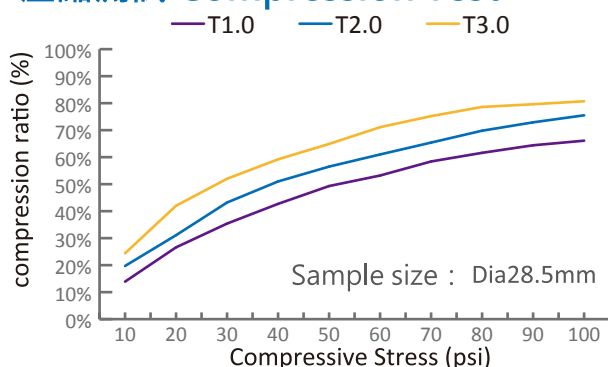
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-35	MP-35Y	MP-35FB	Unit	Test Method
顏色 Color	Pink	Purple	Pink+Yellow	---	Visual
厚度 Thickness	0.25~25	0.25~5.0	0.5~25	mm	ASTM D374
導熱係數 Thermal conductivity	3.0	4.0	3.0	W/mk	ASTM D5470
比重 Specific Gravity	2.3±0.2	2.5±0.2	2.5±0.2	g/cm ³	ASTM D792
延展率 Elongation	<150±10	<250±10	<1	%	ASTM D412
抗拉強度 Tensile Strength	13±3	3±3	70±3	Kgf/cm ²	ASTM D412
硬度 Hardness	15±3	6±4	15±3	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹³	>10 ¹⁴	>10 ¹⁴	ohm•cm	ASTM D257
耐電壓 Insulation Strength	>5.0	>10.0	>8.0	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-45~200	-45~200	°C	---

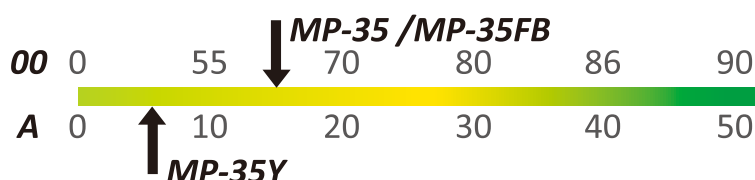
* 測試片標準厚度為1mm以上。 The thickness of the test piece is more than 1 mm.

壓縮測試 Compression Test

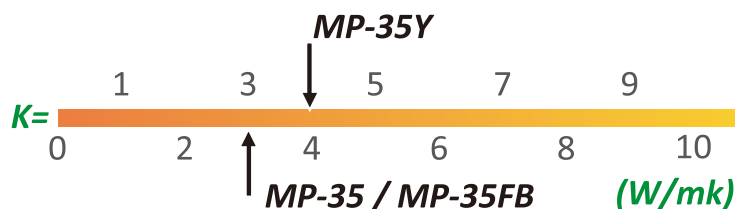


The compression ratio of MP-35Y T2.0 at 50 psi is about 56.5%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



備註 Remark

*可添加玻璃纖維增強機械性
(P/N: MP-35FG、MP-35YFG、MP-35FGFB)
Can add with fiberglass reinforced.

*雙面皆可背膠 (A1 / A2)
Can add with adhesive on one or two sides.



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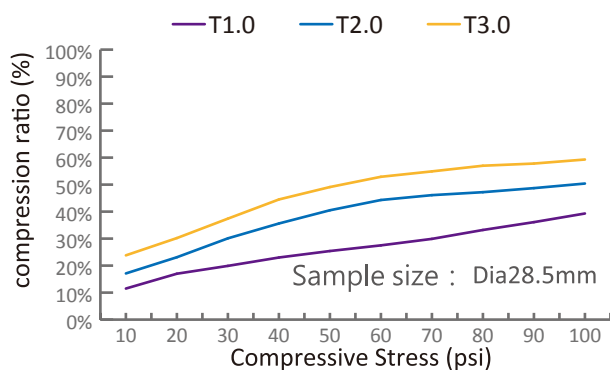
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-45	MP-45Y	MP-45FB	MP-45B	Unit	Test Method
顏色 Color	Blue	Blue	Blue+Yellow	Blue	---	Visual
厚度 Thickness	0.25~25	0.3~7.0	0.5~25	0.5~3.0	mm	ASTM D374
導熱係數 Thermal conductivity	4.0	4.0	4.0	6.0	W/mk	ASTM D5470
比重 Specific Gravity	2.6±0.2	2.44±0.2	2.7±0.2	3.24±0.2	g/cm ³	ASTM D792
延展率 Elongation	<220±10	130	<1	50±10	%	ASTM D412
抗拉強度 Tensile Strength	7±3	1	75±3	1.6	Kgf/cm ²	ASTM D412
硬度 Hardness	18±3	6±2	18±3	9±2	Shore A	ASTM D2240
重量損失 Weight Loss	<1	-	<1	-	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹²	>10 ¹³	>10 ¹³	>10 ¹³	ohm•cm	ASTM D257
耐電壓 Insulation Strength	>4.5	15.0	>6.0	16	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-40~160	-45~200	-50~200	°C	---
耐燃等級 Flame Rating	V-0	-	-	V-0	---	UL94

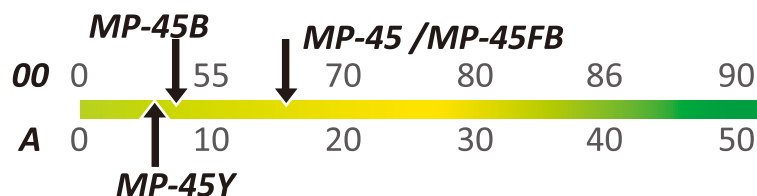
* 測試片標準厚度為1mm以上。 The test specimen is at least 1 mm thick.

壓縮測試 Compression Test

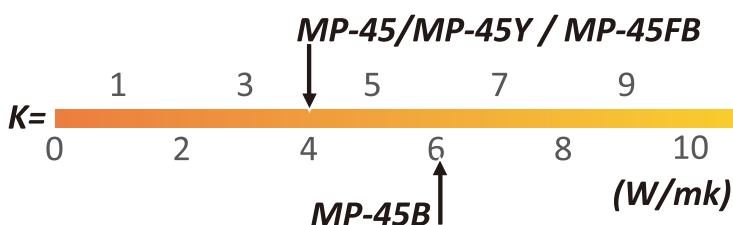


The compression ratio of MP-45FB T2.0 at 50 psi is about 40.5%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



備註 Remark

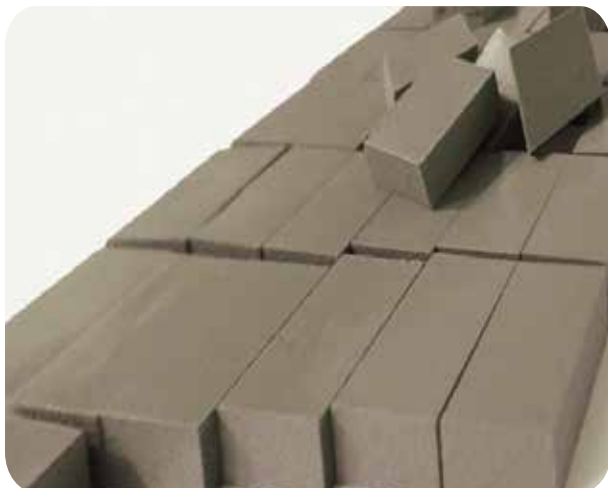
*MP-45 / MP-45FB 可添加玻璃纖維增強機械性
(P/N: MP-45FG、MP-45FGFB)
Can add with fiberglass reinforced.

*除了MP-45Y& MP-45B外，雙面皆可背膠 (A1 / A2)
Only MP-45&MP-45FB can add with adhesive
on one or two sides.





Thermal Silicone Pad



特色 Characteristic

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高耐電壓值 Good insulator
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多種厚度可選擇 Available in varies thickness

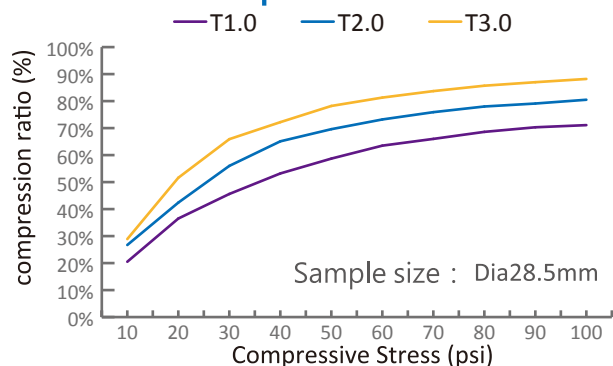
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-55	MP-55Y	Unit	Test Method
顏色 Color	Gary	Gary	---	Visual
厚度 Thickness	0.5~25	0.25~5.0	mm	ASTM D374
導熱係數 Thermal conductivity	5.5	6.0	W/mk	ASTM D5470
比重 Specific Gravity	2.65±0.2	2.65±0.2	g/cm ³	ASTM D792
延展率 Elongation	<220±10	<220±10	%	ASTM D412
抗拉強度 Tensile Strength	7±3	7±3	Kgf/cm ²	ASTM D412
硬度 Hardness	40±3	4±3	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹²	>10 ¹²	ohm•cm	ASTM D257
耐電壓 Insulation Strength	>4.5	>4.5	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-45~200	°C	---

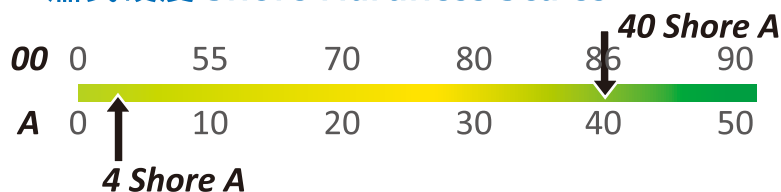
* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

壓縮測試 Compression Test

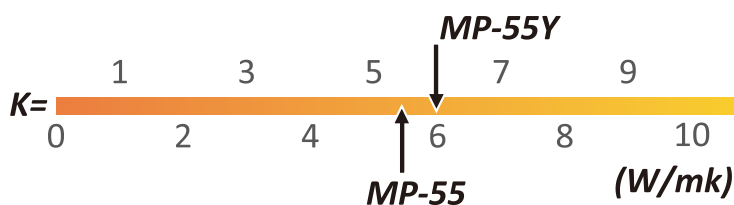


The compression ratio of MP-55Y T2.0 at 50 psi is about 69.6%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



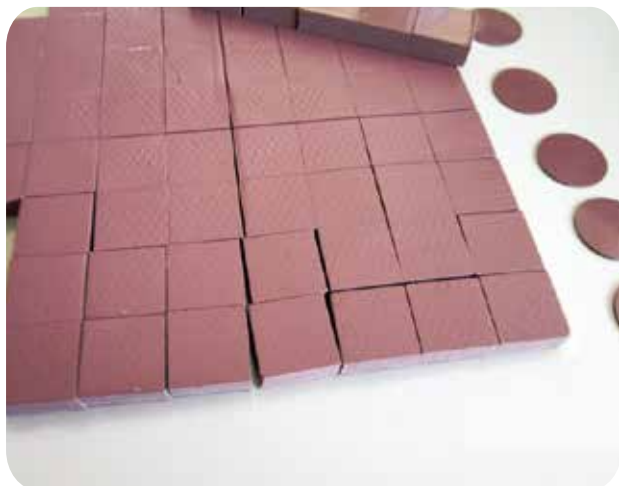
備註 Remark

- *可添加玻璃纖維增強機械性 (P/N: MP-55YFG)
Can add with fiberglass reinforced.
- *MP-55雙面皆可背膠 (A1 / A2)
Only MP-55 can add with adhesive on one or two sides.





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- 高耐電壓值 Good insulator
- 可當緩衝材使用 Shock & vibration absorber
- 多種厚度可選擇 Available in varies thickness

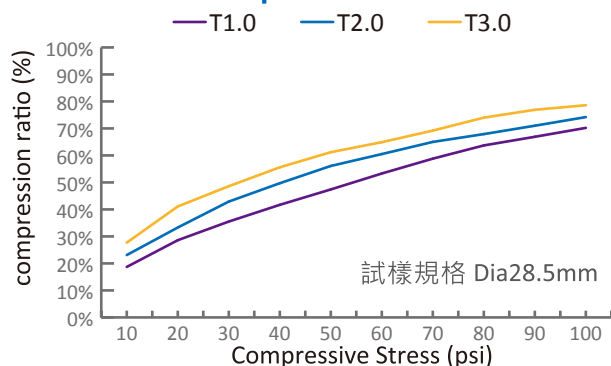
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-70	MP-70Y	Unit	Test Method
顏色 Color	Dark red	Pink	---	Visual
厚度 Thickness	0.25~25	0.3~3.0	mm	ASTM D374
導熱係數 Thermal conductivity	7.0	7.0	W/mk	ASTM D5470
比重 Specific Gravity	3.0±0.2	3.24±0.2	g/cm ³	ASTM D792
延展率 Elongation	<250±10	50±10	%	ASTM D412
抗拉強度 Tensile Strength	5±3	1.6	Kgf/cm ²	ASTM D412
硬度 Hardness	10±3	9±2	Shore A	ASTM D2240
重量損失 Weight Loss	<1	-	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹¹	>10 ¹³	ohm·cm	ASTM D257
耐電壓 Insulation Strength	>4.5	16	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-50~200	°C	---

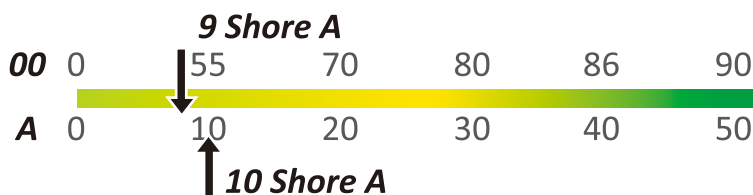
* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

壓縮測試 Compression Test

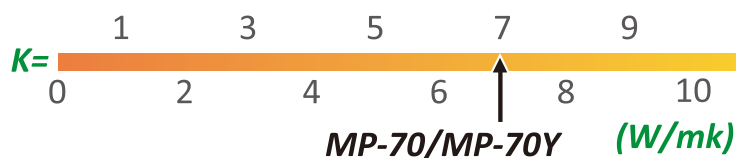


The compression ratio of MP-70 T2.0 at 50 psi is about 56.1%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



備註 Remark

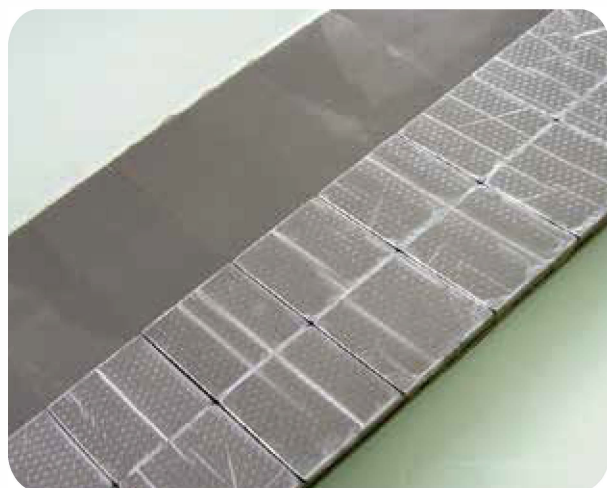
- * MP-70 可添加玻璃纖維增強機械性 (P/N: MP-70FG)
MP-70 can add with fiberglass reinforced.
- * MP-70Y 不能另外加背膠
The surface of MP-70Y cannot coat with adhesives.





Thermal Silicone Pad

導熱矽膠



特色 Characteristic

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- 高耐電壓值 Good insulator
- 可當緩衝材使用 Shock & vibration absorber
- 多種厚度可選擇 Available in varies thickness

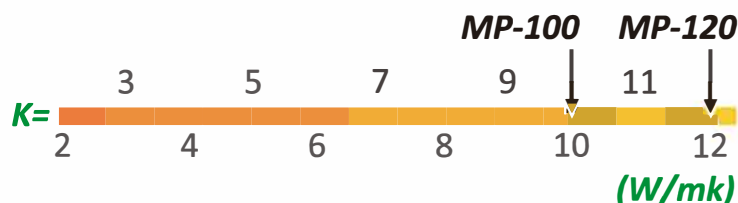
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-100	MP-120	Unit	Test Method
顏色 Color	Dark gary	Gray	---	Visual
厚度 Thickness	0.25~5.0	0.5~3.0	mm	ASTM D374
導熱係數 Thermal conductivity	10.0	12.0	W/mk	ASTM D5470
比重 Specific Gravity	2.9±0.2	3.45±0.2	g/cm ³	ASTM D792
延展率 Elongation	<250±10	30±5	%	ASTM D412
抗拉強度 Tensile Strength	5±3	0.7	Kgf/cm ²	ASTM D412
硬度 Hardness	12±3	10±2	Shore A	ASTM D2240
重量損失 Weight Loss	<1	-	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹¹	>10 ¹³	ohm•cm	ASTM D257
耐電壓 Insulation Strength	>3.5	16	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-50~200	°C	---

* 測試片標準厚度為1mm以上。 The test specimen is at least 1 mm thick.

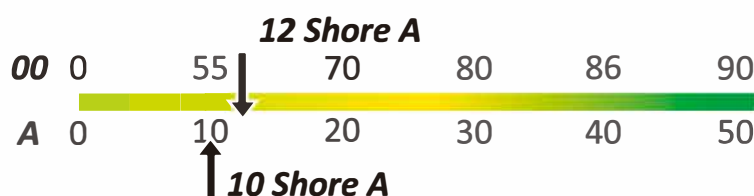
導熱係數 Thermal conductivity



備註 Remark

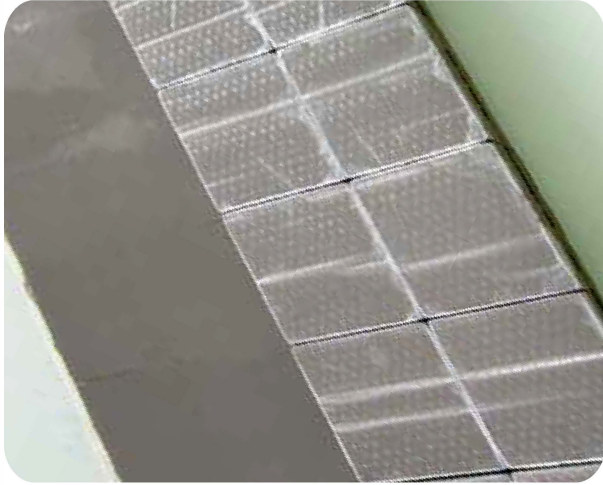
- *MP-100 可添加玻璃纖維增強機械性 (P/N: MP-100FG)
MP-100 can add with fiberglass reinforced.
- *不可以加背膠
Pressure Sensitive Adhesive is not applicable.

蕭氏硬度 Shore Hardness Scales





Thermal Silicone Pad



特色 Characteristic

- 具導熱性 Thermal conductive
- 高柔軟性及高壓縮性高 High soft and compressible
- 自黏性佳 2-sided inherent surface tack.
- 高耐電壓值 Good insulator
- 可當緩衝材使用 Shock & vibration absorber
- 多種厚度可選擇 Available in varies thickness

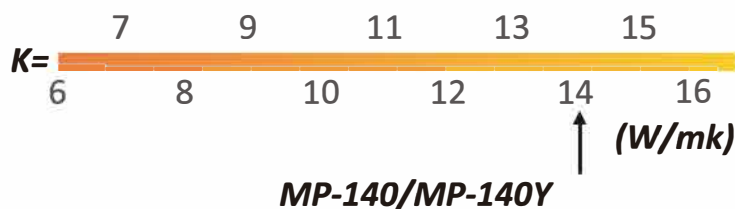
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

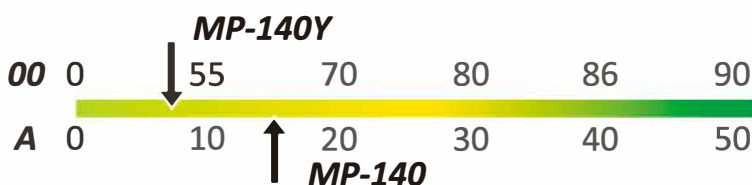
物性 Properties	MP-140	MP-140Y	Unit	Test Method
顏色 Color	Dark Gray	Dark Gray	---	Visual
厚度 Thickness	0.5~2.0	1.0~3.0	mm	ASTM D374
導熱係數 Thermal conductivity	14	14	W/mk	ASTM D5470
比重 Specific Gravity	3.55	3.55	g/cm ³	ASTM D792
延展率 Elongation	20	20	%	ASTM D412
抗拉強度 Tensile Strength	10	10	psi	ASTM D412
硬度 Hardness	60	40	Shore 00	ASTM D2240
介電常數 Dielectric Constant	9	9	1	ASTM D150
體積電阻 Volume Resistivity	>10 ¹³	>10 ¹³	ohm•cm	ASTM D257
耐電壓 Insulation Strength	> 10	> 10	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-50~200	-50~200	°C	---

* 測試片標準厚度為1mm以上。 The test specimen is at least 1 mm thick.

導熱係數 Thermal conductivity



蕭氏硬度 Shore Hardness Scales

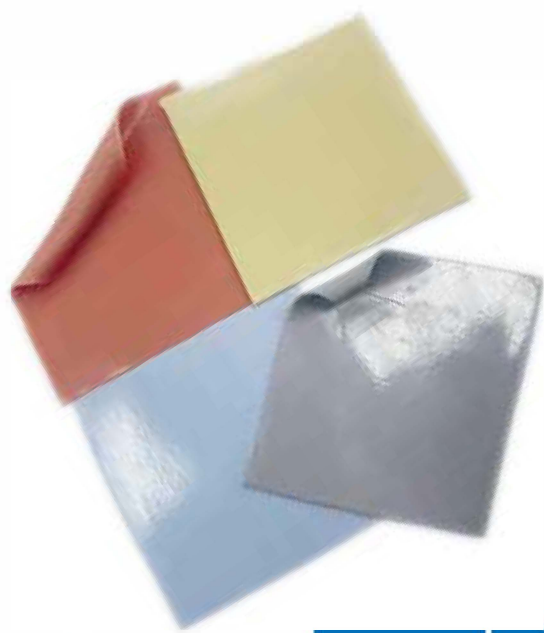


備註 Remark

- * 不可以加背膠
Pressure Sensitive Adhesive is not applicable.
- * 自黏性佳
Excellent natural tack
- * 本系列的產品可以替代Fujipoly Xr-j 使用。
They can be alternative to Fujipoly Xr-j
- * 價格比效能類似的日系品牌低
High C/P value



Non-Silicone Soft Thermal pad



特 色 Characteristic

不含矽膠/矽油 Silicone-free. Polyolefin based.
具導熱&自黏性 Thermal conductive, natural tack
高柔軟性 High soft. Low-stress applications.
高耐電壓值 Good insulator.
可當緩衝材使用 Shock & vibration absorber.
多種厚度可選擇 Available in varies thickness.

適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物 性 Properties	NS-20	NS-30	NS-50	NS-80	Unit	Test Method
顏 色 Color	Pink	Yellow	Blue-gray	Gray	—	Visual
厚 度 Thickness	0.5~5.0	0.5~5.0	1.0~2.0	1.0~2.0	mm	ASTM D374
比 重 Specific Gravity	2.5	2.8	3	3.2	g/cm ³	ASTM D792
溫度範圍 Application temperature	-40~125	-40~125	-40~125	-40~125	°C	—
硬 度 Hardness	30	40	30	60	Shore 00	ASTM D2240
導熱係數 Thermal Conductivity	2.0	3.0	5.0	8.0	W/mk	ASTM D5470
熱 阻 @ 0.5mm Thermal Impedance	0.45	0.37	0.2	0.15	°C-in ² /W	ASTM D5470
體積抗阻 Volume Resistivity	>10 ¹³	>10 ¹³	>10 ¹³	>10 ¹³	Ωcm	ASTM D257
耐電壓值 Breakdown Voltage	>10	>10	>10	>10	KV/mm	ASTM D149
介電常數 Dielectric Constant	6	7	7	8	1	ASTM D150
抗拉強度 Tensile strength	20	15	10	10	psi	ASTM D412
延展率 Elongation	50	40	30	20	%	ASTM D412



Thermal Conductive Silicone Glass Fiber



特色 Characteristic

具導熱性 Thermal conductive.
高耐電壓值 Good insulator.
可當緩衝材使用 Shock & vibration absorber.
高機械強度 Good mechanical strength.

適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	FB-25	Unit	Test Method
顏色 Color	Yellow or Gary or Pink	---	Visual
厚度 Thickness	0.17 / 0.25 / 0.45	mm	ASTM D374
導熱係數 Thermal conductivity	1.3	W/mk	ASTM D5470
比重 Specific Gravity	2.0±0.2	g/cm ³	ASTM D792
延展率 Elongation	<1	%	ASTM D412
抗拉強度 Tensile Strength	50	Kgf/cm ²	ASTM D412
硬度 Hardness	70±5	Shore A	ASTM D2240
重量損失 Weight Loss	<1	%	200°C(48hrs)
體積電阻 Volume Resistivity	10 ¹⁷	ohm·cm	ASTM D257
耐電壓 Insulation Strength	--- / >4.5 / >6.5	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	°C	---

結構 Construction

導熱係數 Thermal conductivity



Glass Fiber Fabrics Sheet



備註 Remark

- * 雙面皆可背膠 (A1 / A2)
Can add with adhesive on one or two sides.
- * 性價比高
High C/P value



High Thermal Conductivity Fiberglass Reinforcement



特 色 Characteristic

低熱阻抗 Low Thermal Contact Resistance.

導熱優、可低壓力應用 Exceptional Thermal Performance At Lower Application Pressures (20psi ~ 400psi).

適溫範圍大 Usable Over a Wide Temperature Range.

施工簡單、減少作業成本

Simplified Processing and Reduced Operating Costs.

適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物 性 Properties	HP1500	HP2000	HP3500	Unit	Test Method
強化物-基材 Reinforcement	Fiberglass	Fiberglass	Fiberglass	—	—
厚 度 Thickness	0.2~0.5	0.2~0.5	0.2	mm	ASTM D374
比 重 Specific Gravity	2.4	2.7	2.9	g/cm ³	ASTM D792
硬 度 Hardness	80	75	80	Shore A	ASTM D2240
熱 阻 Thermal Impedance	0.48	0.28	0.2	°C-in ² /W	ASTM D5470
導熱係數 Thermal Conductivity	1.5	2.2	3.5	W/mk	HOT DISK
體積抗阻 Volume Resistivity	>10 ¹³	>10 ¹³	>10 ¹³	Ωcm	ASTM D257
耐電壓值 Breakdown Voltage	> 3.5	> 3.5	> 3.5	KV	ASTM D149
介電常數 Dielectric Constant	6	7	8	1	ASTM D150
溫度範圍 Application temperature	-50 to 220	-50 to 220	-50 to 220	°C	—
抗拉強度 Tensile strength	> 300	> 300	> 300	psi	ASTM D412
延展率 Elongation	< 10	< 10	< 10	%	ASTM D412



Thermal Putty

特色 Characteristic

高導熱性 High thermal conductivity 4.5W/m.K

高壓縮性 Have enough compressibility.

高絕緣性 Good insulation.

低熱阻 Very low thermal resistance
and good creep performance.

可無限壓縮 It can be infinitely compression.

適用範圍 Usage : Best for north bridge IC.

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD,
Hand-set, Automotive Systems, etc.

物 性	Properties	45G	Unit	Test Method
顏色	Color	Blue	—	Visual
流率	Flow Rate (30cc EFD cartridges 0.100" orifice 90psi)	8	g/min	—
比重	Specific Gravity	3.1	g/cm ³	ASTM D792
矽氧烷揮發物	Siloxane Volatiles D4~D20	<0.01	%	GC-FID
溫度範圍	Application temperature	-50~200	°C	—
導熱係數	Thermal Conductivity	4.5	W/mk	ASTM D5470
熱膨脹係數	Coefficient of Thermal Expansion	175	ppm/K	—
體積抗阻	Volume Resistivity	>10 ¹³	Ωcm	ASTM D257
耐電壓值	Breakdown Voltage	10	KV/mm	ASTM D149
介電常數	Dielectric Constant	8	1	ASTM D150

備註 Remark

*可使用點膠機設備作業
Can be applied with gel gun .

主成份 The main composition of 45G

*矽膠 & 陶瓷粉末

45G base on silicone, Filled with a variety of high-performance ceramic powder made.





Thermal Conductive Grease



特 色 Characteristic

不易乾化 Not easy dry and not harden.

熱傳導最大化 Maximize the heat transfer.

高穩定性 High stability.

容易施工 Easy to assemble.

熱阻低 Very low thermal resistance.

適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, Relay, Power, etc.

物 性 Properties	GC-04	GC-04G	GC-07	Unit	Test Method
顏 色 Color	White	Gray	Gray	-----	Visual
導熱係數 Thermal Conductivity	4.0	5.1	7.0	W/m-k	ASTMD5470
針 入 度 Penetration	280	280	305	mm	ASTM D217
比 重 Specific Gravity	2.8	2.8	2.6	g/cm3	ASTM D1475
熱 阻 抗 Thermal impedance	0.014~0.032	0.012~0.022	0.011~0.017	°C-in2/W	ASTMD5470
油分離度 Oil separation	<0.1	<0.1	<0.05	%	24 hrs at 150°C
黏 度 Viscosity	10 ⁵ ~1.6X10 ⁵	10 ⁵ ~1.6X10 ⁵	1.4X10 ⁵ ~ 1.9X10 ⁵	cps	BrookField HBDV-1 PRIME RVF#7 20RPM
揮 發 份 Volatile component	0.08	0.08	0.16	%	240 hrs at 100°C
溫度範圍 Application temperature	-50~150	-50~150	-50~150	°C	-----

備註 Remark

- * 保存條件：本產品屬於無溶劑性導熱膏
· 建議在室溫中保存。
- * 保存期限：密封且放置在室溫可保存一年。
- * 使用方式：網印、移印.....等。
如產品有出油現象，請攪拌均勻即可使用。
- * 可媲美日系導熱膏
- * 高性價比
- * Storage Conditions：Store in a cool, dry and ventilated area.
- * Stock period：one year (Unopened).
- * Use method：Screen printing, pad printing, etc.
If thermal grease looks oily, please stir it until mix well.
- * Similar performance with Japanese thermal paste
- * High C/P value





Thermal Tape



特色 Characteristic

導熱效能優 Good thermal conductive.
 對金屬、塑膠有良好的黏著性 Good adhesion.
 容易施工 (材質抗撕裂) Easy to assemble.
 客製化 Customize.
 可替代熱固化黏合劑、螺絲扣具之應用
 Alternative for glue and screw

適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
 LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

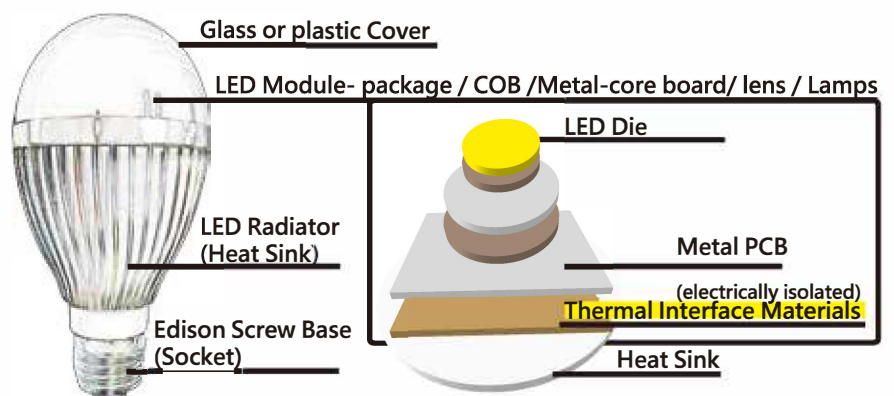
物性 Properties	TP-15	TP-15B	Unit	Test Method
顏色 Color	White	Black	---	Visual
厚度 Thickness	0.1 / 0.15 / 0.25 / 0.35	0.15 / 0.25 / 0.35	mm	ASTM D374
導熱係數 Thermal conductivity	1.1	1.1	W/mk	ASTM D5470
比重 Specific Gravity	1.8±0.2	1.8±0.2	g/cm ³	ASTM D792
硬度 Hardness	25±1	25±1	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	%	---
90° peel test @ 23 °C	- / 20 / 22 / 24	20 / 22 / 24	N / in	ASTM D3330 Method F
90° peel test @ 60 °C	- / 25 / 28 / 29	25 / 28 / 29		
90° peel test @ 115 °C	- / 45 / 50 / 52	45 / 50 / 52		
耐電壓 Insulation Strength	- / >2.5 / >4 / >4.5	>2.5 / >4 / >4.5	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-35~135	-35~135	°C	---

導熱係數 Thermal conductivity

結構 Construction

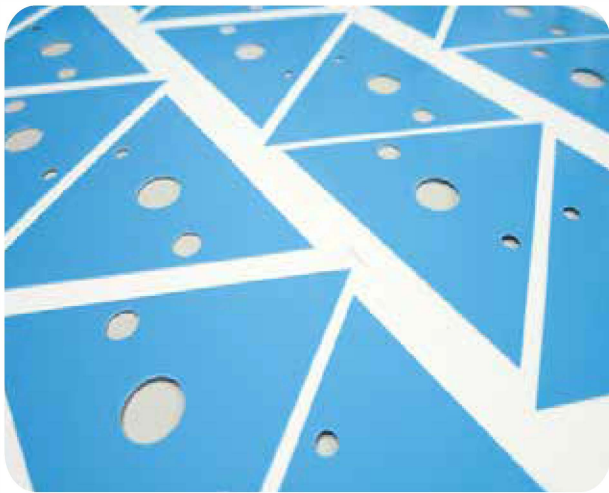


* Structure Illustration :
 Apply thermal interface material
 to LED Module.





Thermal Tape



特色 Characteristic

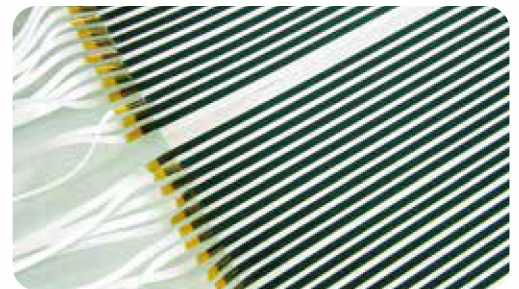
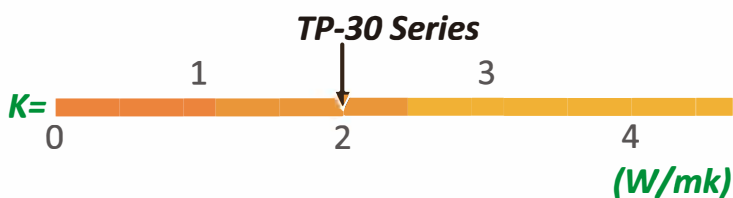
導熱效能優 Good thermal conductive.
 對金屬、塑膠有良好的黏著性 Good adhesion.
 容易施工 (材質抗撕裂) Easy to assemble.
 客製化 Customize.
 可替代熱固化黏合劑、螺絲扣具之應用
 Alternative for glue and screw

適用範圍 Usage

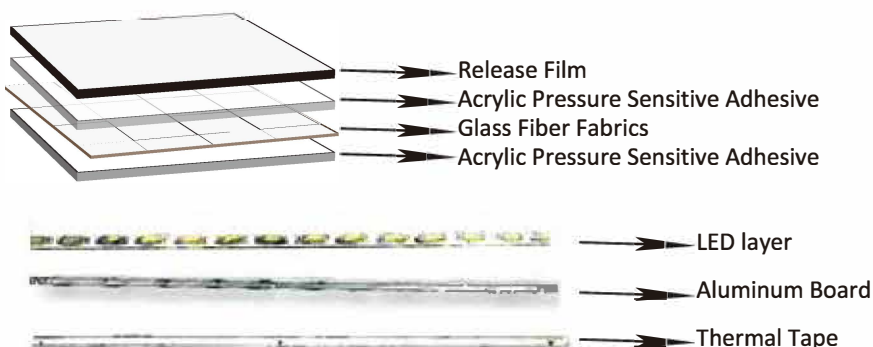
IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink,
 LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	TP-30	TP-30B	Unit	Test Method
顏色 Color	White	Black	---	Visual
厚度 Thickness	0.15 / 0.25	0.15	mm	ASTM D374
導熱係數 Thermal conductivity	2.0	2.0	W/mk	ASTM D5470
比重 Specific Gravity	1.8±0.2	1.8±0.2	g/cm ³	ASTM D792
硬度 Hardness	25±1	25±1	Shore A	ASTM D2240
重量損失 Weight Loss	<1	<1	%	---
90° peel test @ 23 °C	19.5 / 21	19.5	N / in	ASTM D3330 Method F
90° peel test @ 60 °C	23.5 / 26	23.5		
90° peel test @ 115 °C	40 / 47	40		
耐電壓 Insulation Strength	> 3.0 / > 4.0	> 3.0	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-35~135	-35~135	°C	---

導熱係數 Thermal conductivity



結構 Construction



(均溫電磁遮蔽材)

Temperature Uniformity EMI Shielding Material



結構層 Structure Layer

鋁箔 ALUMINUM FOIL

導熱膠 THERMAL ADHESIVE

離型紙 RELEASE PAPER (Peel it off before using)

特點 Features

具導熱性

阻絕電磁波

均溫效果佳

好施工

對鋁料、塑料黏貼性佳。

全遮光性是背光模組產品設計的一大幫手。

具有極佳服貼性，不氧化且不易皺折。

可當石墨替代材

High thermal conductivity

Electromagnetic interference (EMI) shielding

Effective Temperature uniformity

Good workability

Good adhesion for aluminum and plastic product

Good light blocking and insulation for module design

Excellent adhesive and antioxidant

As better alternative for graphite

物性 Properties	EM100B	EM100BT	Unit	Test Method
顏色 Color	Black	Black	---	Visual
厚度 Thickness	0.105±0.015	0.05/0.1 (±0.015)	mm	ASTM D374
導熱係數 Thermal conductivity	XY-axis ,237 Z-axis, >5	XY-axis ,237 Z-axis, >5	W/mk	ASTM D5470
上膠厚度 Coating thickness	0.035±0.002	0.032±0.002	mm	---
上膠量 Coating weight	55±3	55±3	g/cm ²	---
黏著力 <180° peel adhesion	1.5 ↑	1.2 ↑	Kg/25mm	---
剝離力 Release force	15±5	14±5	g/25mm	---
保持力 Holding power	24 ↑	24 ↑	Hr/Kg x 25mm ²	---
耐溫範圍 Use temp. range	-30~160	-30~160	°C	---
保存期限 Stock period	1	1	Year	---

適用範圍 Usage

背光模組、桌上型電腦、NB、手機、電子製品.....等。

Smart phone, I-Pad NB, LED lighting, NB,LED Backlight, CPU,etc.

保存環境 Stock environment

建議保存於乾燥陰涼處 (溫度30°C、濕度60%以下)

30°C×60% RH ↓ IN A COOL、DRY PLACE

標準原材尺寸 Material Standard Sizes

EM100BT: 100M x 630 x T0.1mm

EM100B: 50M x 980 x T0.105mm

專利權 Patent Right

* 中國專利證書 第3757119號

China Patent Certificate Number is "3757119"

* 台灣專利證書 第M 481129號

TAIWAN Patent Certificate Number is "M 481129"



Nano Carbon Copper Film



結構 Structure

	33um	50um	65um	
um	5	5	5	奈米碳導熱塗層 Nano Carbon layer
	18	35	50	銅箔 Copper Foil layer
	10	10	10	導熱膠 Thermal adhesive layer
	140	140	100	離型膜 Release Paper (Peel it off before using)

產品簡介 Brief Description

具有良好導熱性金屬銅為基材，表面複合碳奈米材料，並處理成薄膜化產品，單面粘膠方式的熱輻射銅箔散熱膜，其效果優於原有的傳統工藝的石墨片，散熱性能更加突出，是智慧手機、平板電腦、TV Dongle.....等，散熱的絕佳材料。

Using high thermal conductive copper as the basic material, the surface combined with carbon nanomaterials and processed into thin film products. The heat radiation copper foil with single-sided adhesive is superior to the graphite sheet. The heat dissipation performance is even more prominent. It is an excellent material for applying on smartphones, tablet PCs, TV Dongles, etc.

物 性 Properties	EM100 CU	Unit	Test Method
顏 色 Color	Black	---	Visual
厚 度 Thickness	0.033 / 0.05 / 0.065	mm	ASTM D374
導熱係數 Thermal conductivity	500	W/mk	ASTM D5470
黏 著 力 180° Peel test	1.0 ↑ / 1.5 ↑ / 1.0 ↑	Kg/25mm ²	PSTC-3
初 期 力 Initial Ball Tack test	< 8	cm	PSTC-6 No. 14
阻 燃 性 Flame Rating	VTM-2	---	UL 94
耐溫範圍 Use Temp. range	-20~100	°C	---

標準原材尺寸 Material Standard Sizes : 560mm*100M

產品特點 Features

- * 好的柔韌性、返工、加工性、遮罩電磁干擾，保護敏感的電子零件。
- * 超薄厚度。
- * 可替代石墨片
- * 可模切成任意定制形狀阻絕電磁波。
- * 導熱、均溫效果佳。
- * Flexible, easy to process and re-work, EMI protection for electronic parts (EMI shielding)
- * Ultra-thin thickness
- * As better alternative for graphite
- * Molding in customized shapes to block electromagnetic
- * High thermal conductivity, excellent temperature uniformity spread

可應客戶要求增加此款材料的絕緣特性 Offering Customized Insulation :

絕緣塗層 Insulating layer
奈米碳導熱塗層 Nano Carbon layer
銅箔 Copper Foil layer
絕緣膠 insulating adhesive layer
離型膜 Release Paper (Peel it off before using)



Ceramic Heat Spreader

特色 Characteristic

重量輕 Low weight
 接觸空氣散熱面大 Big air-contact area
 高導熱效能 Good heat spreader
 表面抗組高 High Resistance
 高耐電壓值 High Voltage Breakdown
 適合用於小型設備 Suitable for small devices

適用範圍 Usage

Power Transistor, Power Module, CPU, Chip IC, PC Board, etc.



物性	Properties	CH-22	Unit	Test Method
顏色	Color	Green	---	Visual
尺寸規格	Size	(See page 20)	mm	---
導熱係數	Thermal conductivity	7.2	W/mk	---
比重	Specific Gravity	1.85±0.2	g/cm ³	ASTM D792
表面阻抗	Surface Resistance	>110	ohm	ASTM D257
彎曲強度	Flexural strength	48	Kgf/cm ²	CNS12701
孔隙度	Porosity	30	%	CNS619
硬度	Hardness	5±1	Moh's	DIN En101-1992
熱膨脹係數	Linear Thermal Expansion Coefficient	4.1	10 ⁻⁶	RT-300C
耐電壓	Insulation Strength	>5	KV	ASTM D149
耐溫範圍	Continuous Use Temp	< 500	°C	---
主要成分	Main Composition	Sic / SiO ₂	---	---

結構 Construction

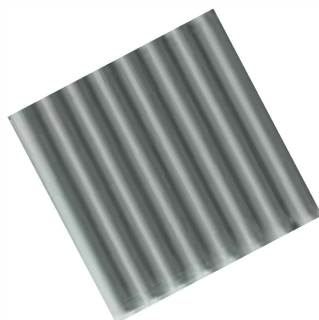
平板 Flat surface

(Thickness from 2.0 to 10.0mm)



波浪 Wave surface

(Thickness from 5.0 to 10.0mm)



凸點 Bump surface

(Thickness from 3.0 to 10.0mm)



Length * width * thickness(mm)

*(F)=Flat surface

*(W)=Wave surface

*(B)=Bump surface



10*10*1.0 (F)



10*10*2.0 (F)



20*15*3.0 (F)



20*15*4.0 (F)



20*15*5.0 (W)



20*15*5.0 (F)



20*20*2.0 (F)



20*20*2.5 (F)



20*20*5.0 (F)



20*20*3.0 (B)



21*21*5.0 (W)



22*22*7.0 (W)



25*25*5.0 (F)



25*25*5.0 (W)



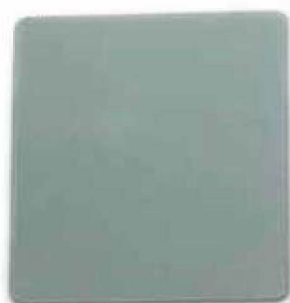
25*25*10.0 (W)



30*30*2.0 (F)



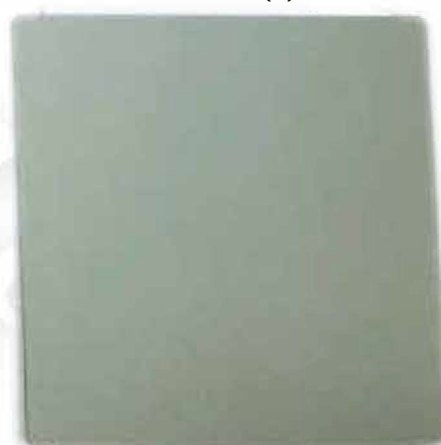
30*30*7.0 (W)



40*40*2.0(F)



50*25*2.0(F)



60*60*2.0(F)



Dia18*T9.0mm



Dia18*T18.0mm



Soft Ceramic Heat Spreader



特色 Characteristic

- 重量輕 Low weight
- 接觸空氣散熱面大 Big air-contact area
- 高導熱效能 Good heat spreader
- 表面抗組高 High Resistance
- 高耐電壓值 High Voltage Breakdown
- 適合用於小型設備 Suitable for small devices
- 軟質材料不易碎化 Not easy to break of soft material

適用範圍 Usage

Power Transistor, Power Module, CPU, Chip IC, PC Board, LED, N/B, M/B, etc.

物 性	Properties	CH-21	Unit	Test Method
顏 色	Color	Green	---	Visual
尺寸規格	Size	(See below)	mm	---
導熱係數	Thermal conductivity	5.0	W/mk	ASTM E5470
比 重	Specific Gravity	2.5	g/cm ³	ASTM D1475
表面阻抗	Surface Resistance	>10 ⁶	ohm	ASTM D257
孔 隙 度	Porosity	10	%	CNS619
硬 度	Hardness	60	Shore A	ASTM D2240
耐 電 壓	Insulation Strength	5	KV/mm	ASTM D149
耐溫範圍	Working Temperature	-40 to 250	°C	---
主要成分	Main Composition	Sic / SiO ₂	---	---
符合RoHS規範	RoHS Compliant	V	---	---
符合REACH規範	REACH Compliant	V	---	---

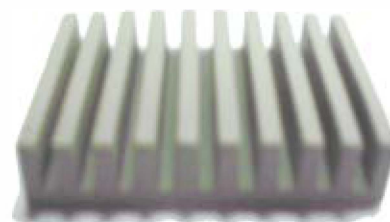
結構 Construction

平板 Flat surface

- * Thickness from 0.25 to 30mm
- * Length=10 to 300 mm, (10mm per gap)
- * Width=10 to 300 mm, (10mm per gap)



鰭片 Fins surface
(L70*W40*T12.0mm)

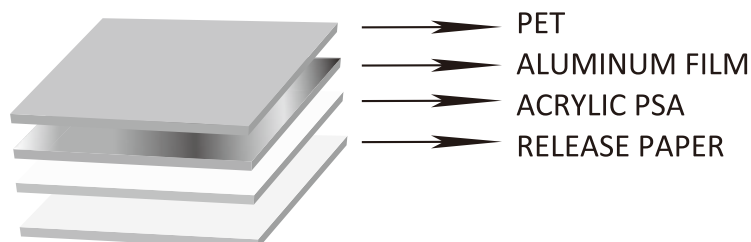




EMI Shielding Tape



結構 Structure



物性 Properties	EM100	Unit
膠帶厚度 Thickness	0.060	mm
PET 顏色 PET Color	Glossy Black / Matte Black	-----
黏著力 Adhesion	1.2 ↑	Kg/25mm
阻抗 Electrical resistance	0.05 ↑	Ω
耐溫性 Temp. Resistance	-30~150	°C

特色 Characteristic

具有優良再加工性。

對鋁料、塑料黏貼性佳。

絕緣效果佳，上絕緣下導通。

全遮光性是背光模組產品設計的一大幫手。Blocking 100 % of LED light.

具有極佳服貼性，不氧化且不易皺折。

阻絕電磁波

Good workability.

Good adhesion for aluminum and plastic product.

Good light blocking and insulation for module design.

Blocking 100 % of LED light.

Excellent adhesive and antioxidant

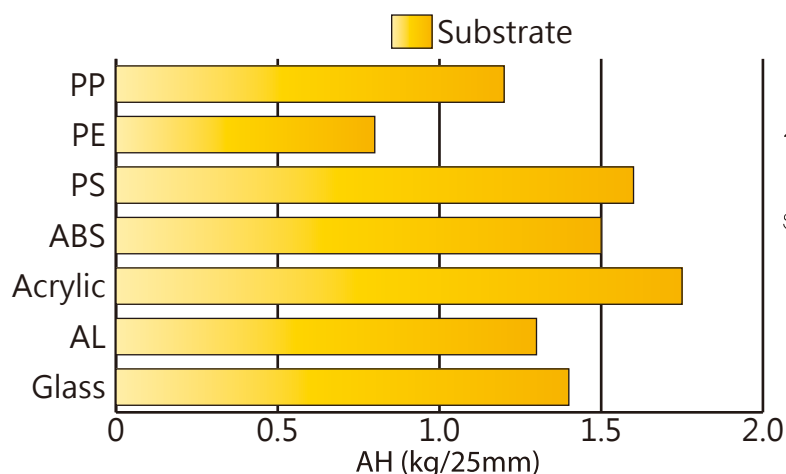
Electromagnetic interference (EMI) shielding

適用範圍 Usage

背光模組、桌上型電腦、NB、手機、電子製品絕緣遮蔽。

Applied to DESKTOP PC, NB & CELL PHONE, lighting module, electromagnetic shielding, average temperature.

對不同貼著材質之黏著強度 180 degree peeling adhesion for each substrate



∠180° 剝離黏著力之測試方法依ASTM D1000 (ASTM D1000, ∠180° peeling adhesion)

Sample : W25mm x 100mm

拉力方向



測試基材

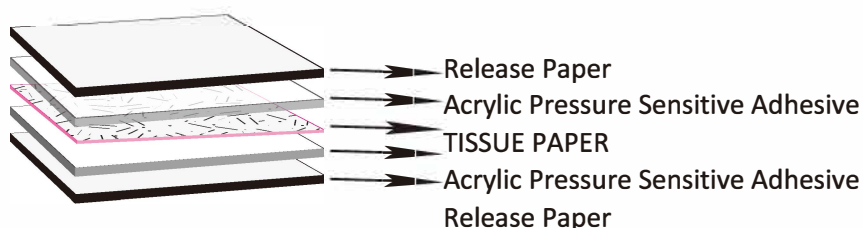




Tissue Double Side Tape 棉材雙面膠帶



結構 Construction



適用範圍 / Usage

銘板、標示牌等固定用。泛用型固定用，針對低表面材質。

Widely use in fixing component. For fixing nameplate.

物 性 Properties	TP-PP	FAT5000	Unit
顏 色 Color	Semi-transparent		---
總 厚 度 Total thickness	0.15±0.01		mm
保 持 力 Holding Power	24 ↑		hr/Kgx25mm ²
初 期 力 Initial ball tack	#28 ↑	#7 ↑	No./ BaALL
∠180°黏著力 Peel Adhesion	2.0 ↑	1.5 ↑	Kg/25mm
適用溫度 Temperature range	-20~120	20~150	°C
棉質基材厚度 Tissue Thickness	0.029±0.003	0.065±0.005	mm
膠 系 Adhesive base	Acrylic Pressure sensitive adhesive		---
剝離力 Release Force	20±10 , 10±5		g/25mm
特 色 Characteristic	可作為一般黏著劑替代品。 對塑料黏著性佳，耐候性佳，易沖型加工， 對於工業用觸控類銘版及汽車用泡棉貼著有良好的效果。 <i>Good adhesion for plastic product. Good temp. resistance and die-cutting. Good bonding for nameplate & foam.</i> 具有優良再加工性。對塑料黏貼性佳，高抗張強度，耐高溫性佳。 強韌的不織布基材具有再撕除的膠性，提高重工的加工使用性。 <i>Good workability. Good adhesion for plastic product. Easy removal and high tension.</i>		---

* 保存期限 Stock Period : ONE YEAR

* 保存環境 Stock environment : 30°C×60% RH ↓ IN A COOL、DRY PLACE





PET Non-Halogen PET (Masking Light) Tape

特 色 / Characteristic

符合電子級無鹵規範、SVHC限用物質規範。
具有優良再加工性。
對鋁料、塑料黏貼性佳。
高溫環境下提供穩定的接合性。

高溫保持力 1440 ↑ (min in 0.5kg × 80°C)。

耐溫，耐化學藥品及紫外光等特性佳。

耐溫 -20~130°C。

對低能量表面有良好之貼合性。

Conform to Halogen-free & SVHC-free.

Good workability.

Good adhesion for aluminum and plastic product.

Good bonding at high temperature.

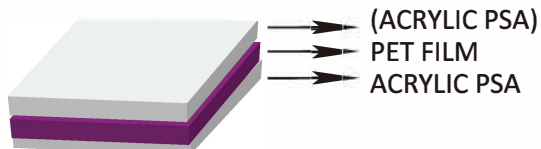
High temp. Holding power 1440 ↑.

Good temperature, chemical & UV resistance.

Resistance Temp. -20~130°C

Good bonding to low surface energy material.

結構 / Construction



適用範圍 / Usage

手機、大型顯示器、筆記型電腦等電子產品零件組裝固定。

Applied on NB, Tablet PC, TFT-LCD display, cell phone etc.

雙面 (遮蔽) 膠帶 Double Side Tape

TF200W		
膠帶厚度 Thickness (mm)	顏色 Color	黏著力 Adhesion kg/25mm
0.030	Transparent	0.8 ↑
0.053	Transparent	1.1 ↑
0.080	Transparent	1.2 ↑
0.102	Transparent	1.4 ↑
0.120	Transparent	1.6 ↑
0.157	Transparent	1.8 ↑

★ Thermal Conductivity=0.6 W/mk

TF200B		
膠帶厚度 Thickness (mm)	顏色 Color	黏著力 Adhesion kg/25mm
0.035	Black	0.8 ↑
0.053	Black	1.1 ↑
0.080	Black	1.2 ↑
0.102	Black	1.4 ↑
0.120	Black	1.6 ↑
0.157	Black	1.8 ↑

★ Blocking 99.9% light

絕緣單面膠帶 Insulating Single Side Tape

TF200W-S		
膠帶厚度 Thickness (mm)	顏色 Color	黏著力 Adhesion kg/25mm
0.045	Transparent	0.8 ↑
0.075	Transparent	1.0 ↑
0.045	White	1.2 ↑
0.070	White	1.4 ↑

TF200W-BS		
膠帶厚度 Thickness (mm)	顏色 Color	黏著力 Adhesion kg/25mm
0.030	Black	0.9 ↑
0.050	Black	1.1 ↑
0.080	Black	1.2 ↑

★ Blocking 99.9% light

One Component Cured Thermally Conductive Adhesive

MX-08 為常溫硬化、單液矽膠，常用於電器絕緣。不會產生腐蝕性物質也不會腐蝕金屬，於固化時黏著於大部分材質，具有極佳的耐冷性、耐候性以及電器特性，符合電子安規。

MX-08 is one-component, room temperature cure thermally conductive adhesive. It possesses good heat conduction and adhesion towards electronic components. It possesses high thermal conductivity, excellent electrical insulation and is ready-to-use. Will not cause corrosion on any surface. Good temp. resistance, water resistance. Compliance requirements for all electrical products used.

特 色 Characteristic

表面乾爽時間短 Initial curing time (tack-free time)=20min.

可黏著於多數的材質 Good adhesion for all kinds of materials

抗化性與耐水性佳 Good chemical resistance, water resistance.

使用溫度範圍廣 Can be applied over a very wide temperature range. (-40°C~200°C)

具有熱傳導功效 Good thermal conductivity (K=1.7W/m-k)

可重工、施工 Good maneuverability. Easy application.

應用 Massive application

Electronic components-IC, CPU, MOS,

Power, LED, M/B, PS, Heat Sink,

LCD-TV, NB, PC, etc.

DDR II Module, DVD Applications, etc.

Include construction, automotive,

marine, assembly, maintenance,

electrical/electronic, aerospace, etc.

物 性	Properties	MX-08	Unit	Conditional
顏色、外觀	Color, Appearance	White paste	---	Visual
表面乾爽時間	Tack-free time	20	25°C/min	RH=85%、厚度Thickness <1 cm
硬化時間	Cure time (Final curing period)	72~168	25°C/hrs	RH=85%、厚度Thickness <1 cm
收 縮 率	shrinkage	3	%	---
比 重	Specific Gravity	2.2	---	---
硬 度	Hardness	85	Shore A	---
拉伸強度	Tensile Strength	20	KG/cm ²	AL/AL
吸 水 率	Water Absorption	0.1	%	24Hrs
體積電阻	Volume Resistivity	> 10 ¹⁴	Ohm.cm	---
熱傳導係數	Thermal Conductivity	1.7	W/mk	---
介電強度	Dielectric Strength	26	KV/mm	---
線性熱膨脹	Coeff. Of Linear Thermal Expansion	5x10 ⁻⁵	cm/cm°C	5~150°C

保存條件 Storage : 1 year

未開封且儲存於25°C以下，乾燥通風避免面陽光直射。

Store in a cool (below 25°C), dry place with tip cap sealed.

使用方式 Instruction of use

1) 將包裝管的頭部切開，裝上尖頭。 Cut the sealed and put a nozzle on.

2) 使用矽膠擠壓槍或點膠機適當擠壓。 Apply the adhesive onto cleaned surface by gel gun.

3) 待其不流動後才可移動。 Please do not move it before glue is fully cured.

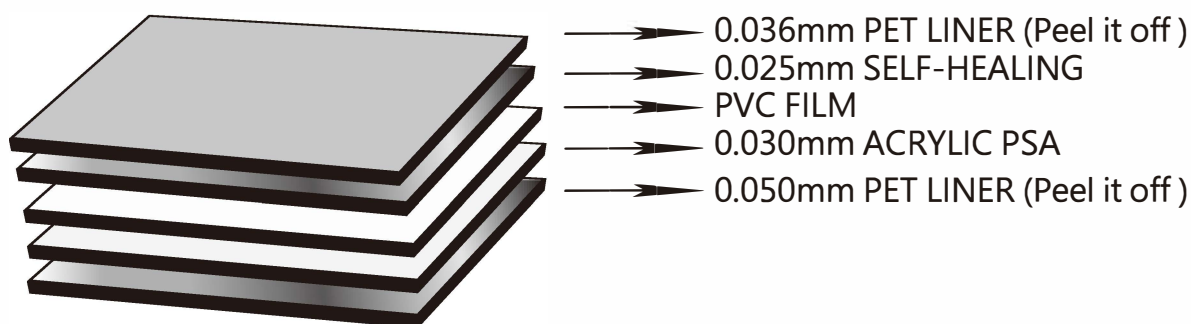


Automotive Paint Protection Film

車用/手機/車燈保護貼

Self-healing in 10 seconds

結構 Structure



產品說明 Brief Description

是由透明彈性體所構成的壓克力膠保護貼應用產品，具有優良的透明度與可修復特性，適合車體保護貼應用。

It is an acrylic adhesive protection made of transparent elastomeric.

It has excellent transparency and reparability and is suitable for Auto Wraps.

產品特色 Features

使用透明彈性體材料，光穿透度佳，貼著撕起不殘膠。

具有良好延展性能，表層具有自我修復功能。

耐候性佳，不會產生霧化現象。

超薄厚度。

Clearly transparent, leaves no residue after applying and tearing up.

Excellent extension ability and self-healing on the surface.

Good weatherability and no foggy.

Ultra-thin thickness

物 性	Properties	IMPU08	IMTV06	Unit	Test Method
顏 色	Color	transparent	transparent	---	Visual
PVC 膜厚度	PVC Thickness	0.14	0.08	mm	ASTM D1000
產品總厚 (SELF+PVC+ACR.)	Total Thickness	0.195 ± 0.005	0.135 ± 0.005	mm	ASTM D1000
可回復測試	Self-healing test	< 10sec	< 10sec	---	Copper brush test
黏著力(壓)	Adhesion	500~700	800 ↑	g/25mm	ASTM D3330
光穿透度	Transmittance	85 ↑	85 ↑	%	ASTM D1003
適用溫度	Use Temp	10 ~ 80	10 ~ 80	°C	---

保存期限 Shelf life

23 °C及65%相對溼度下12個月

12 months <23 °C and 65% relative humidity



Silicone Foam Materials

Brief Description 簡述

PR-1000 is the I.M Tech research and development of silicone foam materials used for high temperature and high pressure. We have different hardness and thickness specifications can be the user's flexible choice.

At the same time, we can choose to join the fiberglass to increase the stability of the product size and improve the tear strength.

艾美研發的矽膠發泡材料，專門提供給高溫高壓的密封環境中所應用。我們有不同的硬度以及厚度規格來提供更靈活的選擇。同時，也可以選擇加入玻璃纖維來增加尺寸的穩定性和增加產品的撕裂強度。

物 性 Properties	PR-1000	Unit	Test Method
顏 色 Color	Dark Gray	---	Visual
厚 度 Thickness	0.75~5.0	mm	ASTM D374
壓 縮 量 Compression Ratio @20psi	20	%	ASTM D395B
抗拉強度 Tensile Strength	45	psi	ASTM D412
硬 度 Hardness	30	Shore C	ASTM D2240
撕裂強度 Tear Strength	8.8	KN/m	ASTM D624
介電常數 Dielectric Constant	1.4	MHz	ASTM D149
介電強度 Dielectric Strength	80	Volts/mil	ASTM D150
耐溫範圍 Continuous Use Temp	-40~200	°C	---

特 色 Characteristic

能承受高溫200°C	Can withstand high temperature 200 °C
良好的緩衝和高壓縮量	Good cushioning and high compression
抗紫外線、臭氧	Resistance to ultraviolet light、ozone
提供增強的密封性能	Provides enhanced sealing performance
使用壓縮後恢復良好	Compressed after using a good recovery
可替代3M VHB	As an Alternative to 3M VHB

適用範圍 Usage

電動汽車動力電池	Car Battery
交通設備	Traffic Equipment
通信與電氣設備	Communication & Electrical Equipment
充電樁	Charging Pile

備註 Remark

* 雙面皆可背膠 (A1 / A2)

Can add with adhesive on one or two sides.